















INA139, INA169

JAJSCM5F – DECEMBER 2000 – REVISED FEBRUARY 2017

## INA1x9ハイサイド計測電流シャント・モニタ

## 1 特長

- 完全なユニポーラ・ハイサイド電流測定回路
- 広い電源電圧範囲と同相電圧範囲
- INA139: 2.7V~40V
- INA169: 2.7V~60V
- 独立した電源電圧と同相入力電圧
- 1つの抵抗器でゲインを設定可能
- 低い静止電流: 60µA (標準値)
- 5ピン、SOT-23パッケージ

## 2 アプリケーション

- 電流シャント測定:
  - 自動車、電話、コンピュータ
- ポータブル・システムやバッテリ・バックアップ・システム
- バッテリ充電器
- パワー・マネージメント
- 携帯電話
- 高精度電流源

## 3 概要

INA139とINA169は、ハイサイド・ユニポーラ電流シャント・モニタです。同相入力電圧範囲が広く、高速で、静止電流が小さく、小型のSOT-23パッケージに格納されているため、さまざまな用途に使用できます。

同相入力と電源電圧は独立しており、許容電圧範囲は、INA139の場合は2.7V~40V、INA169の場合は2.7V~60Vです。静止電流がわずかに60μAと小さいため、電流測定シャントのどちらの側にも電源を接続でき、誤差を最小限に抑えることができます。

本デバイスは差動入力電圧を電流出力に変換します。 1~100以上の範囲で任意のゲインを設定できる外付けの 負荷抵抗器を使用してこの電流が逆に変換され、電圧値 が得られます。本回路は電流シャント測定向けに設計され ていますが、測定やレベルシフトなど有効なさまざまなア プリケーションにご使用ください。

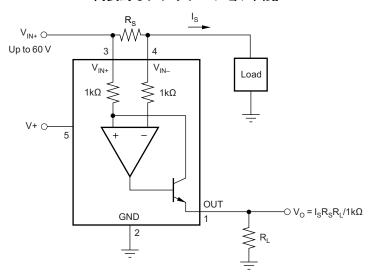
INA139とINA169はどちらも、5ピンのSOT-23パッケージ で供給されます。INA139デバイスは-40 $\mathbb{C}$ ~+125 $\mathbb{C}$ 、INA169は-40 $\mathbb{C}$ ~+85 $\mathbb{C}$ の温度範囲で動作が規定されています。

#### 製品情報<sup>(1)</sup>

	SCHHIDTK	
型番	パッケージ	本体サイズ(typ)
INA139	COT 22 (E)	2.00
INA169	SOT-23 (5)	2.90mm×1.60mm

(1) 利用可能なすべてのパッケージについては、このデータシートの末 尾にある注文情報を参照してください。

## 代表的なアプリケーション回路



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#### 4 改訂履歴

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

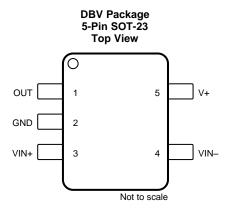
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#### Revision D (November 2005) から Revision E に変更

**Page** 



# **5 Pin Configuration and Functions**



## **Pin Functions**

PIN		I/O	DESCRIPTION					
NAME	NO.	1/0	DESCRIPTION					
GND	2	_	Ground					
OUT	1	0	Output current					
VIN+	3	I	Positive input voltage					
VIN-	4	I	Negative input voltage					
V+	5	I	Power supply voltage					



## 6 Specifications

#### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
Complements on M	INA139	-0.3	60	V
Supply voltage, V <sub>S</sub>	INA169	-0.3	75	V
Angles issues INIA420	Common-mode (2)	-0.3	60	V
Analog inputs, INA139	Differential (V <sub>IN+</sub> ) – (V <sub>IN</sub> –)	-40	2	V
Analog inputs, INA169	Common-mode (2)	-0.3	75	V
	Differential (V <sub>IN+</sub> ) – (V <sub>IN</sub> –)	-40	2	V
Analog input, out (2)		-0.3	40	V
Input current into any pin			10	mA
Operating temperature, T <sub>A</sub>		-55	125	°C
Junction temperature, T <sub>J</sub>			150	°C
Storage temperature, T <sub>stg</sub>		-65	125	°C

<sup>(1)</sup> Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## 6.2 ESD Ratings

			VALUE	UNIT
	Electrostatic discharge Ch	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 (1)	±1000	
V <sub>(ESD)</sub>		Charged-device model (CDM), per JEDEC specification JESD22-C101 (2)	±500	V

<sup>(1)</sup> JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

## 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	NOM	MAX	UNIT
V+	Dower ownsky veltage	INA139	2.7	5	40	\/
	Power-supply voltage	INA169	2.7	5	60	V
	Common mode valtage	INA139	2.7	12	40	\/
	Common-mode voltage	INA169	2.7	12	60	V

<sup>(2)</sup> The input voltage at any pin may exceed the voltage shown if the current at that pin is limited to 10 mA.

<sup>(2)</sup> JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



## 6.4 Thermal Information

		INA1x9	
	THERMAL METRIC <sup>(1)</sup>	DBV (SOT-23)	UNIT
		5 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	168.3	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	73.8	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	28.1	°C/W
ΨЈТ	Junction-to-top characterization parameter	2.5	°C/W
ΨЈВ	Junction-to-board characterization parameter	27.6	°C/W

<sup>(1)</sup> For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.



## 6.5 Electrical Characteristics

INA139: all other characteristics at  $T_A = -40$ °C to +125°C,  $V_+ = 5$  V,  $V_{IN+} = 12$  V, and  $R_{OUT} = 25$  k $\Omega$ , unless otherwise noted INA169: all other characteristics at  $T_A = -40$ °C to +85°C  $V_+ = 5$  V,  $V_{IN+} = 12$  V, and  $R_{OUT} = 25$  k $\Omega$ , unless otherwise noted

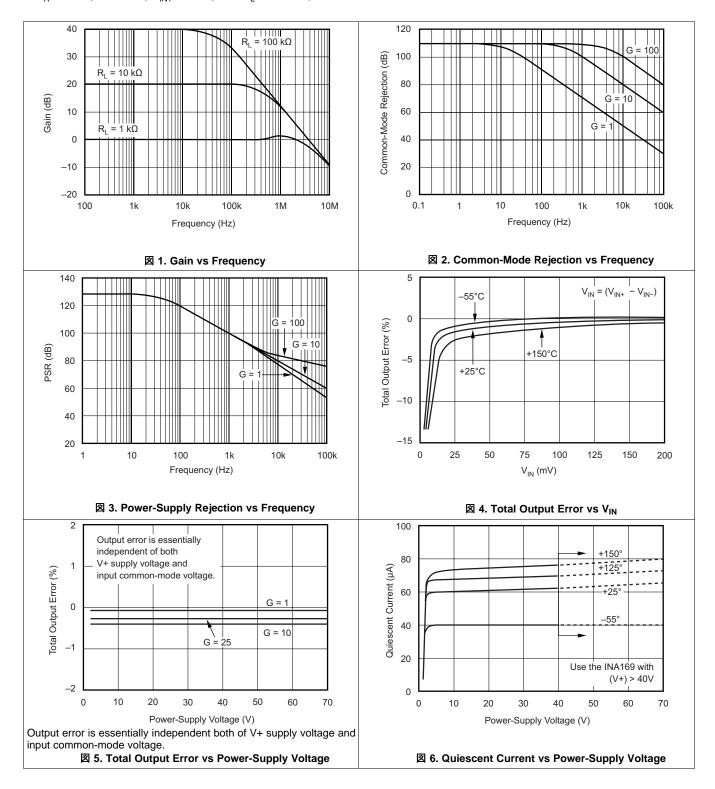
PARAMETER	TEST CONDIT	TIONS	MIN	TYP	MAX	UNIT
INPUT						
Full-scale sense voltage	$V_{SENSE} = V_{IN+} - V_{IN-}$			100	500	mV
On any and a family and a	INA139		2.7		40	
Common-mode input range	INA169		2.7		60	V
	INA139:		99	115		dB
Common-mode rejection	$V_{IN+} = 2.7 \text{ V to } 40 \text{ V}, V_{SEN}$	<sub>SE</sub> = 50 mV				
·	INA169: $V_{IN+} = 2.7 \text{ V to } 60 \text{ V}, V_{SEN}$	<sub>SE</sub> = 50 mV	100	120		dB
O((==1,==1,==== (1) DT)	INA139			±0.2	±1.5	
Offset voltage (1) RTI	INA169			±0.2	±1	mV
vs. temperature	T <sub>MIN</sub> to T <sub>MAX</sub>			1		μV/°C
	INA139: V+ = 2.7 V to 40 V, V <sub>SENSE</sub>	= 50 mV		0.5	10	μV/V
vs power supply (V+)	INA169: V+ = 2.7 V to 60 V, V <sub>SENSE</sub>	= 50 mV		0.1	10	μV/V
Input bias current				10		μA
OUTPUT						
Transcenductores ve temperature	V <sub>SENSE</sub> = 10 mV - 150 mV		990	1000	1010	μA/V
Transconductance vs temperature	V <sub>SENSE</sub> = 10 mV			10		nA/°C
Nonlinearity error	V <sub>SENSE</sub> = 10 mV to 150	INA139		±0.01%	±0.13%	
Nonlinearity error	mV	INA169		±0.01%	±0.1%	
Total output error	V <sub>SENSE</sub> = 100 mV			±0.5%	±2%	
Output impedance				1    5		$G\Omega \parallel pF$
Voltage output	Swing to power supply, V+		(V+) - 0.9	(V+) - 1.2	V	
Vollage output	Swing to common-mode, \	′см		$V_{CM} - 0.6$	V <sub>CM</sub> - 1	· ·
FREQUENCY RESPONSE						
Bandwidth	$R_{OUT} = 10 \text{ k}\Omega$		440		kHz	
Banawian	$R_{OUT} = 20 \text{ k}\Omega$			220		kHz
Settling time (0.1%)	5-V step, $R_{OUT} = 10 \text{ k}\Omega$			2.5		μs
Colling time (0.178)	5-V step, $R_{OUT} = 20 \text{ k}\Omega$			5		μs
NOISE			T.			
Output-current noise density				20		pA/√Hz
Total output-current noise	BW = 100 kHz			7		nA RMS
POWER SUPPLY						
Operating range, V+	INA139		2.7		40	V
INA169			2.7		60	V
Quiescent current	$V_{SENSE} = 0$ , $I_O = 0$			60	125	μΑ
TEMPERATURE RANGE					Т	
Specification, T <sub>MIN</sub> to T <sub>MAX</sub>	INA139		-40		125	°C
	INA169		-40		85	°C
Operating			<b>–</b> 55		125	°C
Storage			-65		150	°C
Thermal resistance, $\theta_{JA}$				200		°C/W

<sup>(1)</sup> Defined as the amount of voltage ( $V_{\mbox{\footnotesize SENSE}}$ ) to drive the output to zero.



## 6.6 Typical Characteristics

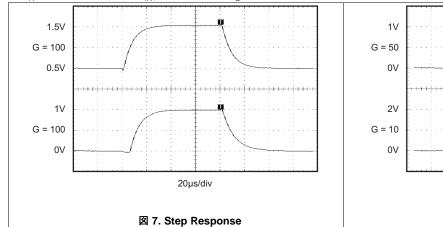
at  $T_A$  = 25°C, V+ = 5 V,  $V_{IN+}$  = 12 V, and  $R_L$  = 125 k $\Omega$ , unless otherwise noted.

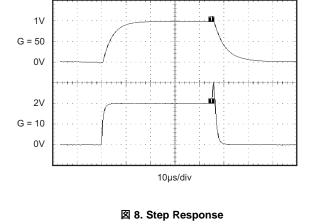


# TEXAS INSTRUMENTS

## **Typical Characteristics (continued)**

at  $T_A$  = 25°C, V+ = 5 V,  $V_{IN+}$  = 12 V, and  $R_L$  = 125 k $\Omega$ , unless otherwise noted.





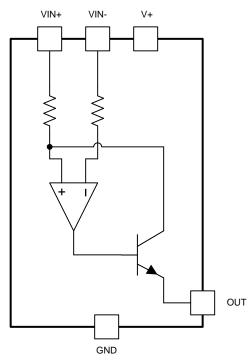


## 7 Detailed Description

#### 7.1 Overview

The INA139 and INA169 devices are comprised of a high voltage, precision operational amplifier, precision thin film resistors trimmed in production to an absolute tolerance and a low noise output transistor. The INA139 and INA169 devices can be powered from a single power supply and their input voltages can exceed the power supply voltage. The INA139 and INA169 devices are ideal for measuring small differential voltages, such as those generated across a shunt resistor in the presence of large, common-mode voltages. See the *Functional Block Diagram*, which illustrates the functional components within both the INA139 and INA169 devices.

## 7.2 Functional Block Diagram



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#### 7.3 Feature Description

#### 7.3.1 Output Voltage Range

The output of the INA139 is a current, which is converted to a voltage by the load resistor ( $R_L$ ). The output current remains accurate within the *compliance voltage range* of the output circuitry. The shunt voltage and the input common-mode and power-supply voltages limit the maximum possible output swing. The maximum output voltage compliance is limited by the lower of  $\vec{\mathbf{z}}$  1 and  $\vec{\mathbf{z}}$  2.

$$V_{OUTMAX} = (V +) - 0.7 V - (V_{IN+} - V_{IN-})$$
(1)

or whichever is lower

$$V_{OUTMAX} = V_{IN-} - 0.5 V \tag{2}$$



## **Feature Description (continued)**

#### 7.3.2 Bandwidth

Measurement bandwidth is affected by the value of the load resistor ( $R_L$ ). High gain produced by high values of  $R_L$  yield a narrower measurement bandwidth (see the *Typical Characteristics* graphs). For widest possible bandwidth, keep the capacitive load on the output to a minimum. Reduction in bandwidth due to capacitive load is shown in the *Typical Characteristics* graphs.

If bandwidth limiting (filtering) is desired, a capacitor can be added to the output (see 🗵 12). This does not cause instability.

#### 7.4 Device Functional Modes

For proper operation the INA139 and INA169 devices must operate within their specified limits. Operating either device outside of their specified power supply voltage range or their specified common-mode range results in unexpected behavior and is not recommended. Additionally operating the output beyond their specified limits with respect to power supply voltage and input common-mode voltage will also produce unexpected results. See the *Electrical Characteristics* table for device specifications.



## 8 Application and Implementation

注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 8.1 Application Information

#### 8.1.1 Operation

 $\boxtimes$  9 illustrates the basic circuit diagram for both the INA139 and INA169. Load current I<sub>S</sub> is drawn from supply V<sub>S</sub> through shunt resistor R<sub>S</sub>. The voltage drop in shunt resistor V<sub>S</sub> is forced across R<sub>G1</sub> by the internal operational amplifier, causing current to flow into the collector of Q1. The external resistor R<sub>L</sub> converts the output current to a voltage, V<sub>OUT</sub>, at the OUT pin.

The transfer function for the INA139 is given by 式 3:

$$I_{O} = g_{m} \left( V_{IN+} - V_{IN-} \right)$$

where

• 
$$g_m = 1000 \,\mu\text{A/V}$$
 (3)

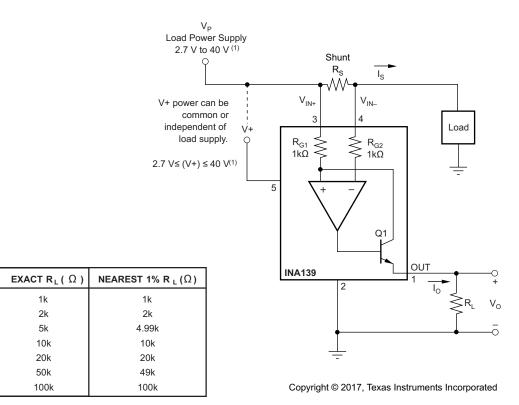
In the circuit of  $\boxtimes$  9, the input voltage  $(V_{IN+} - V_{IN-})$  is equal to  $I_S \times R_S$  and the output voltage  $(V_{OUT})$  is equal to  $I_O \times R_L$ . The transconductance  $(g_m)$  of the INA139 is 1000  $\mu$ A/V. The complete transfer function for the current measurement amplifier in this application is given by  $\pm$  4:

$$V_{OUT} = (I_S)(R_S)(1000 \, \mu A / V)(R_L)$$
(4)

The maximum differential input voltage for accurate measurements is 0.5 V, which produces a 500- $\mu$ A output current. A differential input voltage of up to 2 V will not cause damage. Differential measurements (pins 3 and 4) must be unipolar with a more-positive voltage applied to pin 3. If a more-negative voltage is applied to pin 3, the output current,  $I_O$ , is zero, but it will not cause damage.



#### **Application Information (continued)**



(1) For the INA169 device, maximum  $V_P$  and  $V_T$  voltage is 60 V.

図 9. Basic Circuit Connections

## 8.2 Typical Applications

**VOLTAGE GAIN** 

2

5

10

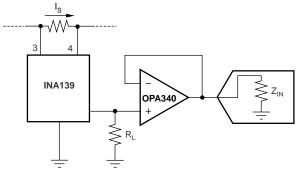
20

50

100

The INA139 is designed for current shunt measurement circuits, as shown in 29, but its basic function is useful in a wide range of circuitry. A creative engineer will find many unforeseen uses in measurement and level shifting circuits. A few ideas are illustrated in 214 through 218.

## 8.2.1 Buffering Output to Drive an ADC



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(1) Buffer of amp drives the A/D converter without effecting gain

図 10. Buffering Output to Drive the A/D Converter

#### 8.2.1.1 Design Requirements

Digitize the output of the INA139 or INA169 devices using a 1-MSPS analog-to-digital converter (ADC).



#### 8.2.1.2 Detailed Design Procedure

#### 8.2.1.2.1 Selecting R<sub>S</sub> and R<sub>L</sub>

In  $\boxtimes$  9 the value selected for the shunt resistor ( $R_S$ ) depends on the application and is a compromise between small-signal accuracy and maximum permissible voltage loss in the measurement line. High values of  $R_S$  provide better accuracy at lower currents by minimizing the effects of offset, while low values of  $R_S$  minimize voltage loss in the supply line. For most applications, best performance is attained with an  $R_S$  value that provides a full-scale shunt voltage of 50 mV to 100 mV; maximum input voltage for accurate measurements is 500 mV.

 $R_L$  is selected to provide the desired full-scale output voltage. The output impedance of the INA139 and INA169 OUT terminal is very high, which permits using values of  $R_L$  up to 100  $k\Omega$  with excellent accuracy. The input impedance of any additional circuitry at the output must be much higher than the value of  $R_L$  to avoid degrading accuracy.

Some analog-to-digital converters (ADCs) have input impedances that significantly affect measurement gain. The input impedance of the ADC can be included as part of the effective  $R_L$  if the input can be modeled as a resistor to ground. Alternatively, an operational amplifier can be used to buffer the ADC input, as shown in  $\boxtimes$  10. The INA139 and INA169 are current output devices, and have an inherently large output impedance. The output currents from the amplifier are converted to an output voltage through the load resistor ( $R_L$ ) connected from the amplifier output to ground. The ratio of the load resistor value to that of the internal resistor value determines the voltage gain of the system.

In many applications, digitizing the output of the INA139 or INA169 devices is required. This is accomplished by connecting the output of the amplifier to an ADC. It is very common for an ADC to have a dynamic input impedance. If the INA139 or INA169 output is connected directly to an ADC input, the input impedance of the ADC is effectively connected in parallel with the gain setting resistor (R<sub>L</sub>.) This parallel impedance combination affects the gain of the system and the impact on the gain is difficult to estimate accurately. A simple solution that eliminates the paralleling of impedances, simplifying the gain of the circuit is to place a buffer amplifier (such as the OPA340) between the output of the INA139 or INA169 devices and the input to the ADC.

☑ 10 illustrates this concept. A low-pass filter can be placed between the OPA340 output and the input to the ADC. The filter capacitor is required to provide any instantaneous demand for current required by the input stage of the ADC. The filter resistor is required to isolate the OPA340 output from the filter capacitor to maintain circuit stability. The values for the filter components vary according to the operational amplifier used for the buffer and the particular ADC selected. For more information regarding the design of the low-pass filter, see the 16-bit 1-MSPS Data Acquisition Reference Design for Single-Ended Multiplexed Applications TI Precision Design.

☑ 11 shows the expected results when driving an analog-to-digital converter at 1 MSPS with and without buffering the INA139 or INA169 output. Without the buffer, the high impedance of the INA139 or INA169 reacts with the input capacitance and sample and hold (S/H) capacitance of the analog-to-digital converter and does not allow the S/H to reach the correct final value before the S/H resets and the next conversion starts. Adding the buffer amplifier significantly reduces the output impedance driving the S/H and allows for higher conversion rates than can be achieved without adding the buffer.

#### 8.2.1.3 Application Curve

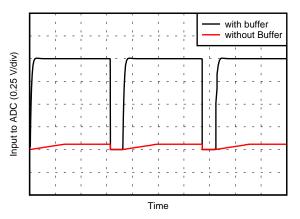
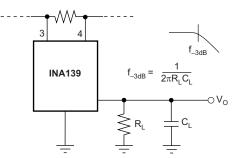


図 11. Driving an ADC With and Without a Buffer

## 8.2.2 Output Filter



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図 12. Output Filter

## 8.2.2.1 Design Requirements

Filter the output of the INA139 or INA169 devices.

#### 8.2.2.2 Detailed Design Procedure



#### 8.2.2.3 Application Curve

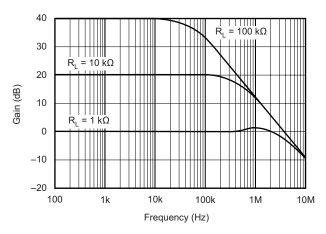
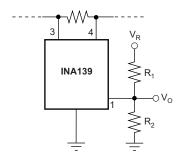
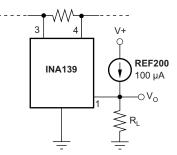


図 13. Gain vs Frequency

#### 8.2.3 Offsetting the Output Voltage

For many applications using only a single power supply, it may be required to level shift the output voltage away from ground when there is no load current flowing in the shunt resistor. Level shifting the output of the INA139 or INA169 devices is easily accomplished by one of two simple methods shown in  $\boxtimes$  14. The method on the left hand side of  $\boxtimes$  14 illustrates a simple voltage divider method. This method is useful for applications that require the output of the INA139 or INA169 devices to remain centered with respect to the power supply at zero load current through the shunt resistor. Using this method the gain is determined by the parallel combination of  $R_1$  and  $R_2$ , while the output offset is determined by the voltage divider ratio  $R_1$  and  $R_2$ . For applications that may require a fixed value of output offset independent of the power supply voltage, TI recommends using the current source method shown on the right hand side of  $\boxtimes$  14. With this method, a REF200 constant current source is used to generate a constant output offset. Using this method, the gain is determined by  $R_L$  and the offset is determined by the product of the value of the current source and  $R_1$ .





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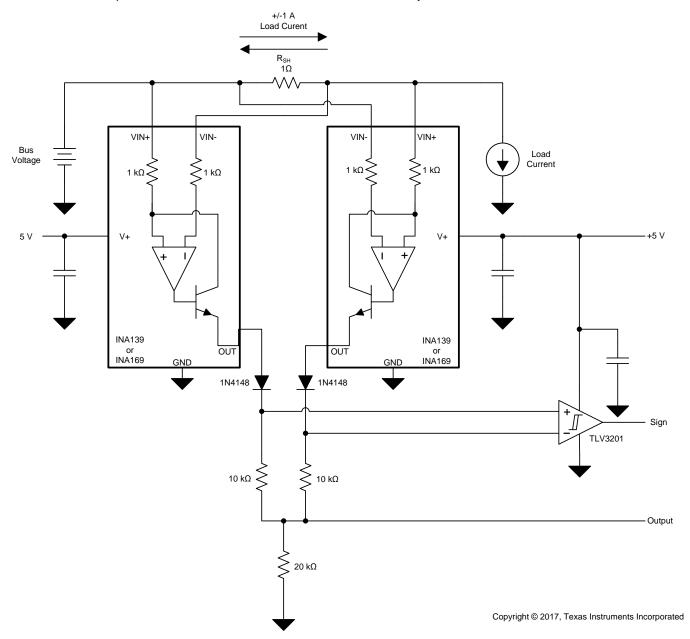
- (1) Gain set by  $R_1 \parallel R_2$ . Output offset =  $(V_R) R_2 / (R_1 + R_2)$  using resistor divider.
- (2) Gain set by  $R_L$ . Output offset = 100  $\mu$ A ×  $R_L$  (independent of V+) using current source.

## ☑ 14. Offsetting the Output Voltage



#### 8.2.4 Bipolar Current Measurement

The INA139 or INA169 devices can be configured as shown in  $\boxtimes$  15 in applications where measuring current bidirectionally is required. Two INA devices are required connecting their inputs across the shunt resistor as shown in  $\boxtimes$  15. A comparator, such as the TLV3201, is used to detect the polarity of the load current. The magnitude of the load current is monitored across the resistor connected between ground and the connection labeled *Output*. In this example the 20-k $\Omega$  resistor results in a gain of 20 V/V. The 10-k $\Omega$  resistors connected in series with the INA139 or INA169 output current are used to develop a voltage across the comparator inputs. Two diodes are required to prevent current flow into the INA139 or INA169 output, as only one device at a time is providing current to the *Output* connection of the circuit. The circuit functionality is illustrated in  $\boxtimes$  16.



☑ 15. Bipolar Current Measurement



#### 8.2.4.1 Application Curve

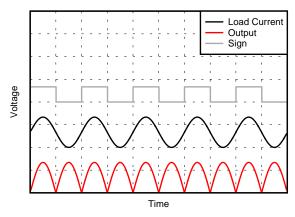
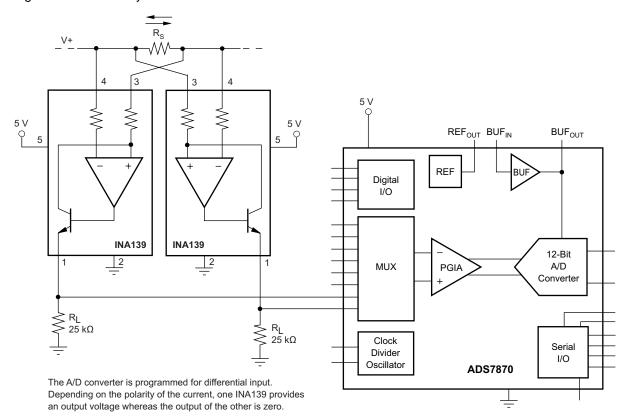


図 16. Bipolar Current Measurement Results (Arbitrary Scale)

#### 8.2.5 Bipolar Current Measurement Using a Differential Input of the A/D Converter

The INA139 or INA169 devices can be used with an ADC such as the ADS7870 programmed for differential mode operation. 

17 illustrates this configuration. In this configuration, the use of two devices allows for bidirectional current measurement. Depending upon the polarity of the current, one of the devices provides an output voltage while the other output is zero. In this way, the ADC reads the polarity of current directly, without requiring additional circuitry.



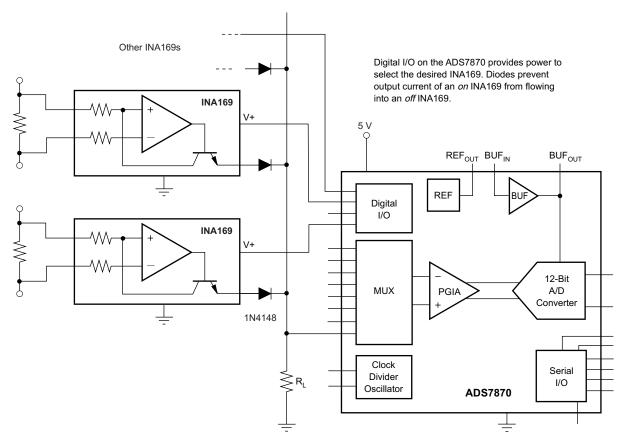
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図 17. Bipolar Current Measurement Using a Differential Input of the A/D Converter



## 8.2.6 Multiplexed Measurement Using Logic Signal for Power

Multiple loads can be measured as illustrated in 🗵 18. In this configuration, each INA139 or INA169 device is powered by the digital I/O from the ADS7870. Multiplex each device by switching the desired I/O on or off.



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図 18. Multiplexed Measurement Using Logic Signal for Power

## 9 Power Supply Recommendations

The input circuitry of the INA139 can accurately measure beyond the power-supply voltage (V+). For example, the V+ power supply can be 5 V, whereas the load power supply voltage is up to 40 V (or 60 V with the INA169). However, the output voltage range of the OUT terminal is limited by the lesser of the two voltages (see the *Output Voltage Range* section). TI recommends placing a 0.1-µF capacitor near the V+ pin on the INA139 or INA169. Additional capacitance may be required for applications with noisy supply voltages.



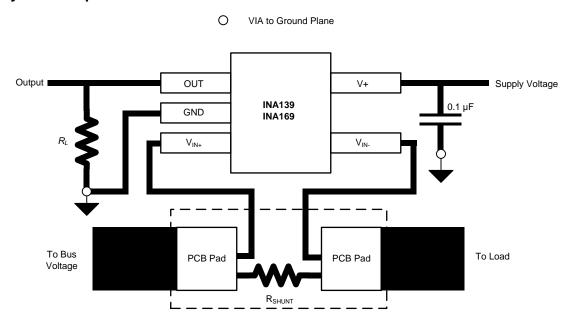
## 10 Layout

#### 10.1 Layout Guidelines

 $\boxtimes$  19 shows the basic connection of the INA139. The input pins ( $V_{IN+}$  and  $V_{IN-}$ ) must be connected as closely as possible to the shunt resistor to minimize any resistance in series with the shunt resistance. The output resistor,  $R_L$ , is shown connected between pin 1 and ground. Best accuracy is achieved with the output voltage measured directly across  $R_L$ . This is especially important in high-current systems where load current could flow in the ground connections, affecting the measurement accuracy.

No power-supply bypass capacitors are required for stability of the INA139. However, applications with noisy or high-impedance power supplies may require decoupling capacitors to reject power-supply noise; connect the bypass capacitors close to the device pins.

#### 10.2 Layout Example



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図 19. Typical Layout Example



## 11 デバイスおよびドキュメントのサポート

#### 11.1 関連リンク

次の表に、クイック・アクセス・リンクを示します。カテゴリには、技術資料、サポートおよびコミュニティ・リソース、ツールとソフトウェア、およびサンプル注文またはご購入へのクイック・アクセスが含まれます。

#### 表 1. 関連リンク

製品	プロダクト・フォルダ	ご注文はこちら	技術資料	ツールとソフトウェア	サポートとコミュニティ
INA139	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
INA169	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック

## 11.2 コミュニティ・リソース

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

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設計サポート *TIの設計サポート* 役に立つE2Eフォーラムや、設計サポート・ツールをすばやく見つけることができます。技術サポート用の連絡先情報も参照できます。

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## 11.5 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

#### 12 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。この情報は、そのデバイスについて利用可能な最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

www.ti.com 10-Nov-2025

#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking
	(1)	(2)			(3)	(4)	(5)		(6)
INA139NA/250	Active	Production	SOT-23 (DBV)   5	250   SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	E39
INA139NA/250.A	Active	Production	SOT-23 (DBV)   5	250   SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	E39
INA139NA/3K	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	E39
INA139NA/3K.A	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	E39
INA169NA/250	Active	Production	SOT-23 (DBV)   5	250   SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	A69
INA169NA/250.A	Active	Production	SOT-23 (DBV)   5	250   SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	A69
INA169NA/3K	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	A69
INA169NA/3K.A	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	A69

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

## PACKAGE OPTION ADDENDUM

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF INA139, INA169:

Automotive: INA139-Q1, INA169-Q1

NOTE: Qualified Version Definitions:

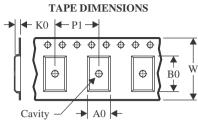
• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

**PACKAGE MATERIALS INFORMATION** 

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## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
INA139NA/250	SOT-23	DBV	5	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
INA139NA/3K	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
INA169NA/250	SOT-23	DBV	5	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
INA169NA/3K	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3



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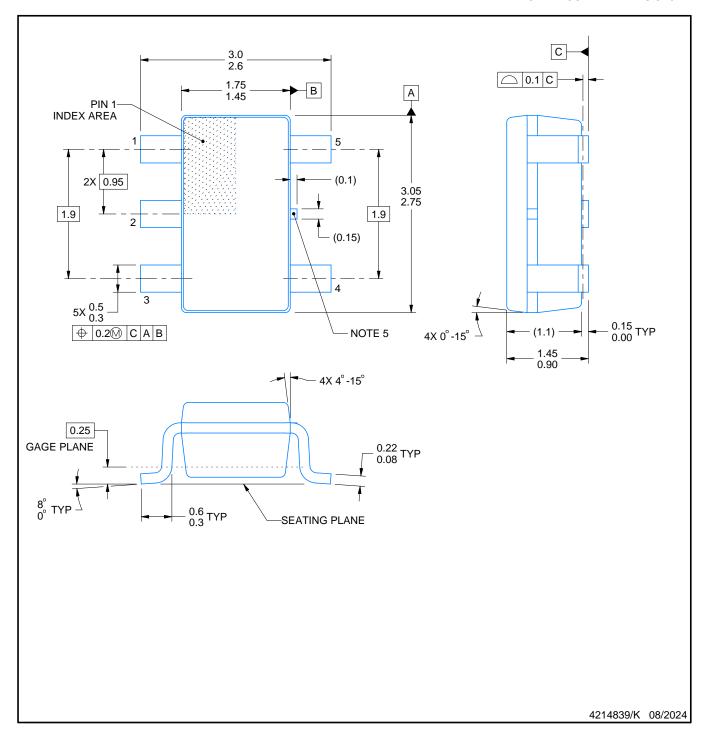


#### \*All dimensions are nominal

The difference and from the								
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
INA139NA/250	SOT-23	DBV	5	250	180.0	180.0	18.0	
INA139NA/3K	SOT-23	DBV	5	3000	180.0	180.0	18.0	
INA169NA/250	SOT-23	DBV	5	250	180.0	180.0	18.0	
INA169NA/3K	SOT-23	DBV	5	3000	180.0	180.0	18.0	



SMALL OUTLINE TRANSISTOR



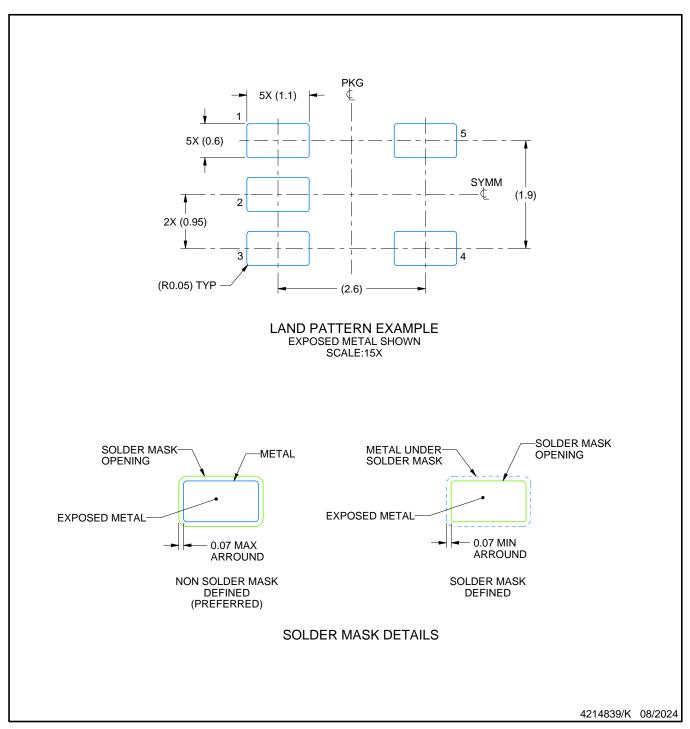
#### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
  2. This drawing is subject to change without notice.
  3. Reference JEDEC MO-178.

- 4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
- 5. Support pin may differ or may not be present.



SMALL OUTLINE TRANSISTOR



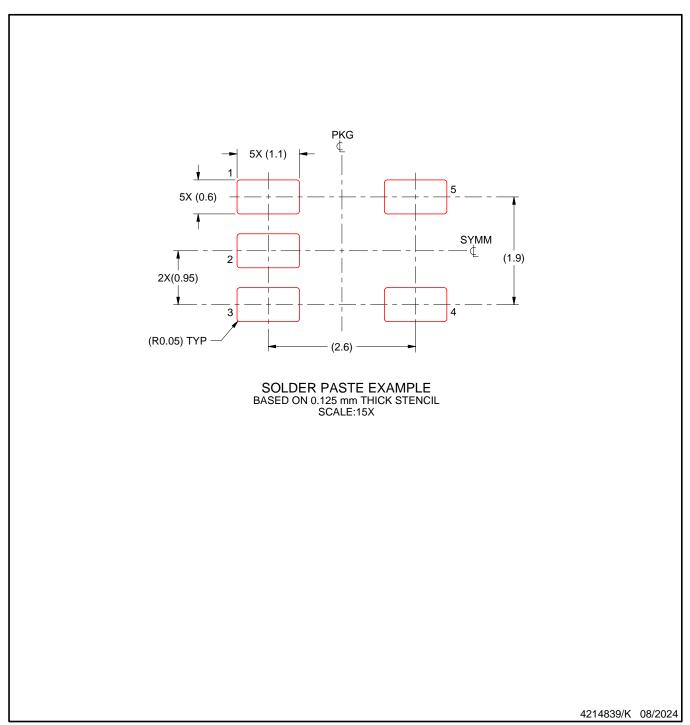
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE TRANSISTOR



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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